



PATENT

2827\$

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: 09/826,512  
Filed: April 5, 2001  
Title: Wiring Substrate, Method of Manufacturing  
Same and Semiconductor Device  
Inventors: Michio Horiuchi et al.  
Atty. Dkt. No.: 089-01

CERTIFICATE OF MAILING

Date of deposit: September 26, 2002.

I Hereby Certify that this correspondence is  
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Commissioner for Patents, Washington, D.C.  
20231, with sufficient postage for first class mail  
in accordance with 37 C.F.R. § 1.8, on the date  
indicated above.

Name of person depositing paper or fee:  
Denise Logan

SIGNATURE: Denise Logan

Commissioner For Patents  
Washington, D.C. 20231

COVER LETTER WITH CERTIFICATE OF MAIL

Sir:

Enclosed and attached hereto are the following:

- 1) Cover letter with Certificate of Mailing (1 pg.);
- 2) Information Disclosure Statement (2 pgs.);
- 3) Statement under 37 C.F.R. 1.97(e) Accompanying IDS
- 4) PTO-1449 (1 pg.);
- 5) Copies of cited prior art (6 documents);
- 6) Check in the amount of \$180.00 for submission fee; and
- 7) Postcard to be date stamped and returned.

In the event that an additional fee is required with respect to this communication, the Commissioner is hereby authorized to charge any additional fees, or credit any overpayment, to Paul & Paul Deposit Account No. 16-0750. This cover letter is submitted in triplicate.

Respectfully Submitted,

Ourmazd S. Ojan

Date: September 26, 2002

Ourmazd S. Ojan  
Reg. No. 38,065  
Paul & Paul  
2900 Two Thousand Market Street  
Philadelphia, PA 19103  
(215) 568-4900

Order No.: 0911

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**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

*Atto  
Prior art  
FJONES  
10-25-02*

Serial No.: 09/826,512  
Filed: April 5, 2001  
Title: Wiring Substrate, Method for Manufacturing  
Same and Semiconductor Device  
Inventors: Michio Horiuchi et al.  
Atty. Dkt. No.: 089-01

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*Name of person depositing paper or fee:  
Denise Logan*

SIGNATURE: *Denise Logan*

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**INFORMATION DISCLOSURE STATEMENT  
PURSUANT TO 37 C.F.R. 1.97(e)**

Sir/Madam:

Pursuant to the provisions of 37 C.F.R. §§1.56, 1.97 and 1.98, applicant calls the attention of the Examiner to the publications listed on the enclosed sheet of Form PTO-1449. Copies of each publication are submitted herewith. The filing of this Information Disclosure Statement shall not be construed to be an admission that the information cited in the statement is, or is considered to be, material to patentability as described in § 1.56 (b).

It is respectfully requested that the Examiner initial each Form PTO-1449 and return a copy of same upon consideration of these publications.

Each item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Information Disclosure Statement.

10/02/2002 HUUONG1 00000014 09826512

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180.00 DP

PATENT



Docket No. 089-01

**U.S. PATENTS**

<u>Patent No.</u>	<u>Date</u>	<u>Name</u>
5,943,212	Aug 1999	Horiuchi et al.
5,872,393	Feb 1999	Sakai et al.

**FOREIGN PATENTS**

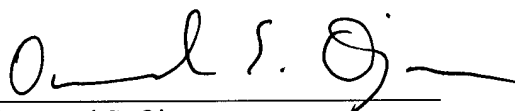
<u>Patent No.</u>	<u>Date</u>	<u>Country</u>
EP 1,030,357 A	Aug 2000	European
WO99/23696 A	May 1999	International
JP 05047842 A	Feb 1993	Japan

**OTHER DOCUMENTS**

Patent Abstracts of Japan, Vol. 017, No. 344 (E-1390), June 29, 1993 (1993-06-29).

Respectfully submitted,

Date: September 26, 2002

  
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**STATEMENT UNDER 37 CFR 1.97(e) ACCOMPANYING  
INFORMATION DISCLOSURE STATEMENT**

Docket No.  
089-01

In Re Application Of: **Michio Horiechi and Takashi Kurihara**

Serial No.  
09/826,512

Filing Date  
April 5, 2001

Examiner

Group Art Unit

Invention: **Wiring Substrate, Method of Manufacturing Same and Semiconductor Device**

TO THE ASSISTANT COMMISSIONER FOR PATENTS:

This is a statement under the provisions of 37 CFR 1.97(e) in the above-identified application.

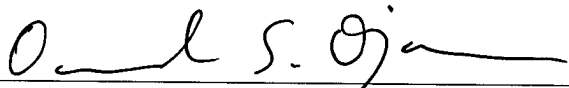
Check applicable statement herebelow:

Statement Under 37 CFR 1.97(e)(1)

- ☒ Each item of information contained in the accompanying information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement.

Statement Under 37 CFR 1.97(e)(2)

- ☐ No item of information contained in the accompanying information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the undersigned person, after making reasonable inquiry, no item of information contained in the accompanying information disclosure statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the information disclosure statement.

  
Signature

Dated: September 26, 2002

**Ourmazd S. Ojan**  
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Philadelphia, PA 19103

I certify that this document is being deposited on  
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20231.

  
Signature of Person Mailing Correspondence

**Denise Logan**

Typed or Printed Name of Person Mailing Correspondence

CC: